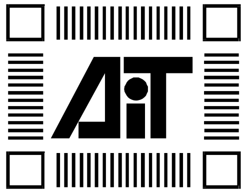

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PRIMA-SOLDER
ME8260-SLV

Pin Transfer
High Strength
Low Thermal Resistance
Electrically Conductive
Epoxy Paste Adhesive

IDEAL FOR:

Stamp or Pin Transfer Die Attach
Conventional Die Attach
Automated Assemblies
Build-In Molecular Stress Relief

DESCRIPTION:

ME8260-SLV is a low viscosity and accelerated version of ME8260 for snap curing applications. This silver filled paste is solvent free, electrically and thermally conductive. It is designed for automated, online die attach processing.

ME8260-SLV is designed for die-attach with stress absorbing capability for sizes up to 2cm. The viscosity has been designed for stamp transfer dispensing of die-attach application.

AVAILABILITY:

ME8260-SLV is available in syringes for automatic needle dispense applications or in jars.

APPLICATION PROCEDURES:

(1) Thaw for 30 minutes before opening jar or using syringes.

(2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.

(3) Cure according to one of the recommended cure schedules.

TYPICAL PROPERTIES*

Property	Value
Electrical Resistivity (150ºC/ 60 minutes)	$<4x10^{-4}$ ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(ºC)	80 ±10%
Current Carrying Capabilities	50 Amp/mm²
Lap-Shear Strength	>1000 psi >6.9 N/mm²
Device Push-off Strength	>2000 psi >13.8 N/mm²
Hardness (Type)	80 (D) ±10%
Cured Density (gm/cc)	3.8 ±10%
Thermal Conductivity	>55 Btu-in/hr-ft²-ºF ±10% >7.9 W/m-ºC ±10%
Linear Thermal Expansion Coeff. (ppm/ºC)	40 ±15%
Maximum Continuous Operation Temp. (ºC)	<150
Pot Life	2 days
Avg. Viscosity(5 rpm, 25ºC) (Brookfield DV-1,Spindle CP51)	8,000 cp (TI~3.5) ±20%
Thixotropic Index	3.0 ±20%

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

CURE SCHEDULES:

Temperature	Time	Pressure
125ºC	>2 hr	
150ºC	>30 min	

For higher temperature wire-bonding than 150ºC, post-curing at the higher temperature is recommended.

SHELF LIFE:

Storage temperature	Shelf Life
-40ºC	1 yr

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

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